



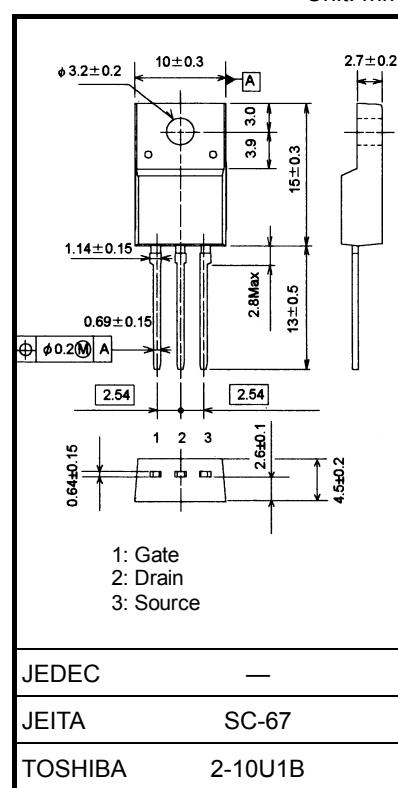
# 2SK4014

DC/DC Converter, Relay Drive and Motor Drive  
Applications

- Low drain-source ON-resistance :  $R_{DS\ (ON)} = 1.6\ \Omega\ (\text{typ.})$
- High forward transfer admittance :  $|Y_{fs}| = 5.0\ \text{S}\ (\text{typ.})$
- Low leakage current :  $I_{DSS} = 100\ \mu\text{A}\ (\text{max})\ (V_{DS} = 720\ \text{V})$
- Enhancement mode :  $V_{th} = 2.0\sim4.0\ \text{V}\ (V_{DS} = 10\ \text{V}, I_D = 1\ \text{mA})$

## Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristic	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	900	V
Drain-gate voltage ( $R_{GS} = 20\ \text{k}\Omega$ )	$V_{DGR}$	900	V
Gate-source voltage	$V_{GSS}$	$\pm 30$	V
Drain current	DC (Note 1)	$I_D$	A
	Pulse (Note 1)	$I_{DP}$	A
Drain power dissipation ( $T_c = 25^\circ\text{C}$ )	$P_D$	45	W
Single-pulse avalanche energy (Note 2)	$E_{AS}$	972	mJ
Avalanche current	$I_{AR}$	6	A
Repetitive avalanche energy (Note 3)	$E_{AR}$	15	mJ
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature range	$T_{stg}$	-55~150	$^\circ\text{C}$



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

## Thermal Characteristics

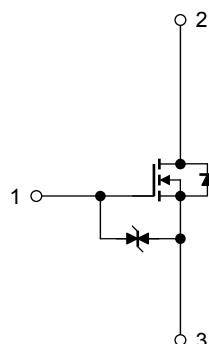
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th\ (ch-c)}$	2.78	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th\ (ch-a)}$	62.5	$^\circ\text{C} / \text{W}$

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 90\ \text{V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 49.5\ \text{mH}$ ,  $R_G = 25\ \Omega$ ,  $I_{AR} = 6\ \text{A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



**Electrical Characteristics (Ta = 25°C)**

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	—	—	±10	µA	
Gate-source breakdown voltage	V (BR) GSS	I <sub>G</sub> = ±10 µA, V <sub>DS</sub> = 0 V	±30	—	—	V	
Drain cutoff current	I <sub>DSS</sub>	V <sub>DS</sub> = 720 V, V <sub>GS</sub> = 0 V	—	—	100	µA	
Drain-source breakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	900	—	—	V	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	—	4.0	V	
Drain-source ON-resistance	R <sub>DSD</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A	—	1.6	2.0	Ω	
Forward transfer admittance	Y <sub>fsl</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	—	5.0	—	S	
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	—	1400	—	pF	
Reverse transfer capacitance	C <sub>rss</sub>		—	30	—		
Output capacitance	C <sub>oss</sub>		—	130	—		
Switching time	Rise time	t <sub>r</sub>	 V <sub>GS</sub> 10V 0V 50 Ω ID = 3 A R <sub>L</sub> = 133 Ω V <sub>DD</sub> = 400 V Duty ≤ 1%, t <sub>w</sub> = 10 µs	—	25	—	ns
	Turn-on time	t <sub>on</sub>		—	75	—	
	Fall time	t <sub>f</sub>		—	60	—	
	Turn-off time	t <sub>off</sub>		—	220	—	
Total gate charge (gate-source plus gate-drain)	Q <sub>g</sub>	V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	—	45	—	nC	
Gate-source charge	Q <sub>gs</sub>		—	25	—		
Gate-drain ("Miller") charge	Q <sub>gd</sub>		—	20	—		

**Source-Drain Ratings and Characteristics (Ta = 25°C)**

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	—	—	—	6	A
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	—	—	—	18	A
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V	—	—	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V dI <sub>DR</sub> / dt = 100 A / µs	—	1100	—	ns
Reverse recovery charge	Q <sub>rr</sub>		—	10	—	µC

**Marking**